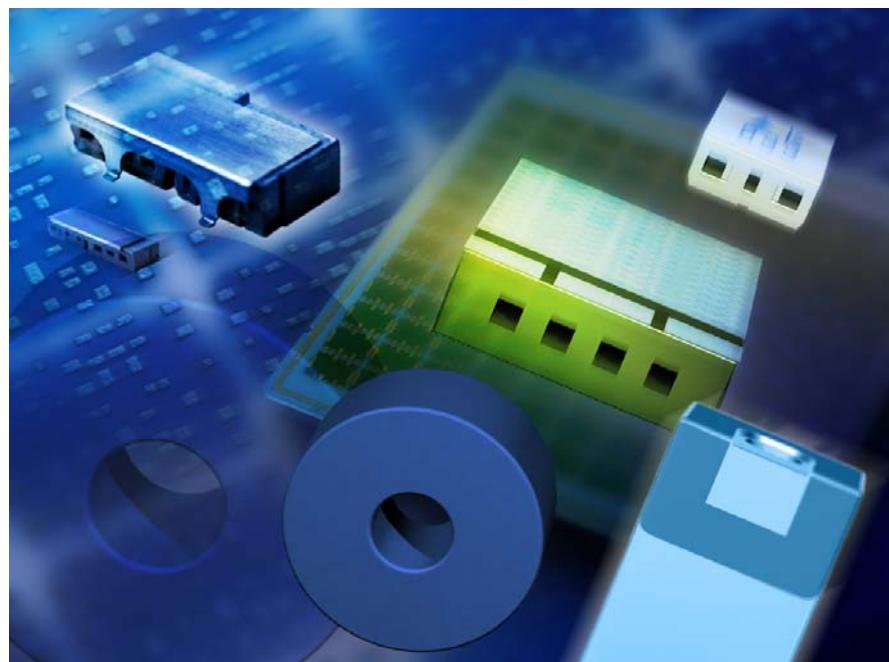


Preliminary Datasheet

Features

- Low Profile (maximum height 1.4mm)
- SMD filter consisting of coupled resonators with stepped impedances
- Low losses
- High attenuations at GSM (900, 1800) and UMTS bands
- High attenuation at 2 times center frequency
- (NdBa)TiO₃ ($\epsilon_r = 88$ / $TC_f = 0 \pm 10$ ppm/K) with a coating of copper (10µm) and tin (>5µm)
- Excellent reflow solderability, no migration effect due to copper/tin metallization

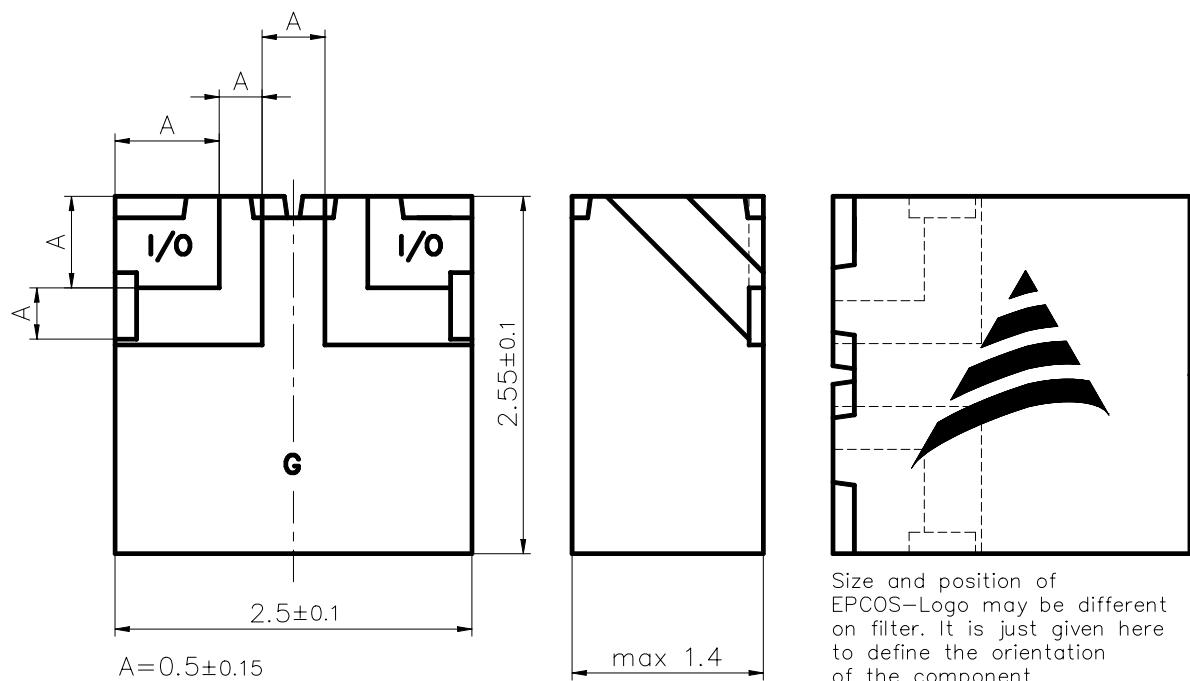
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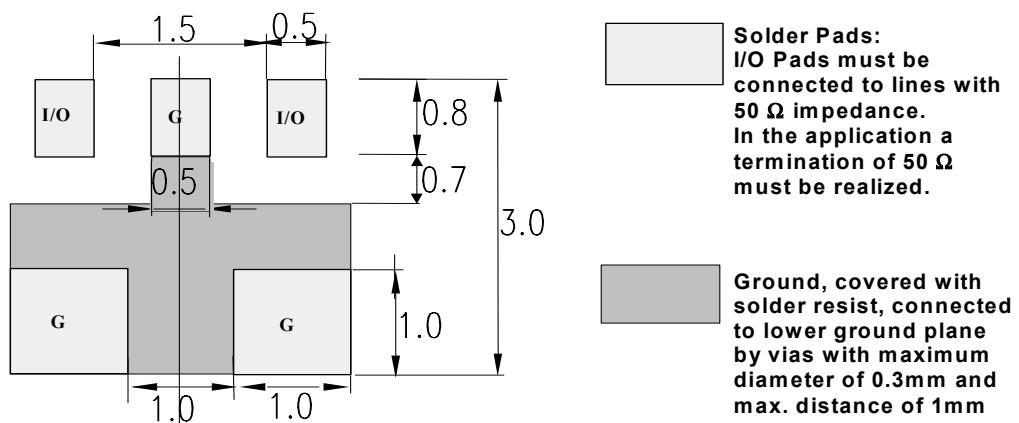
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Preliminary Datasheet

Dimension Limits , Marking



Recommended footprint

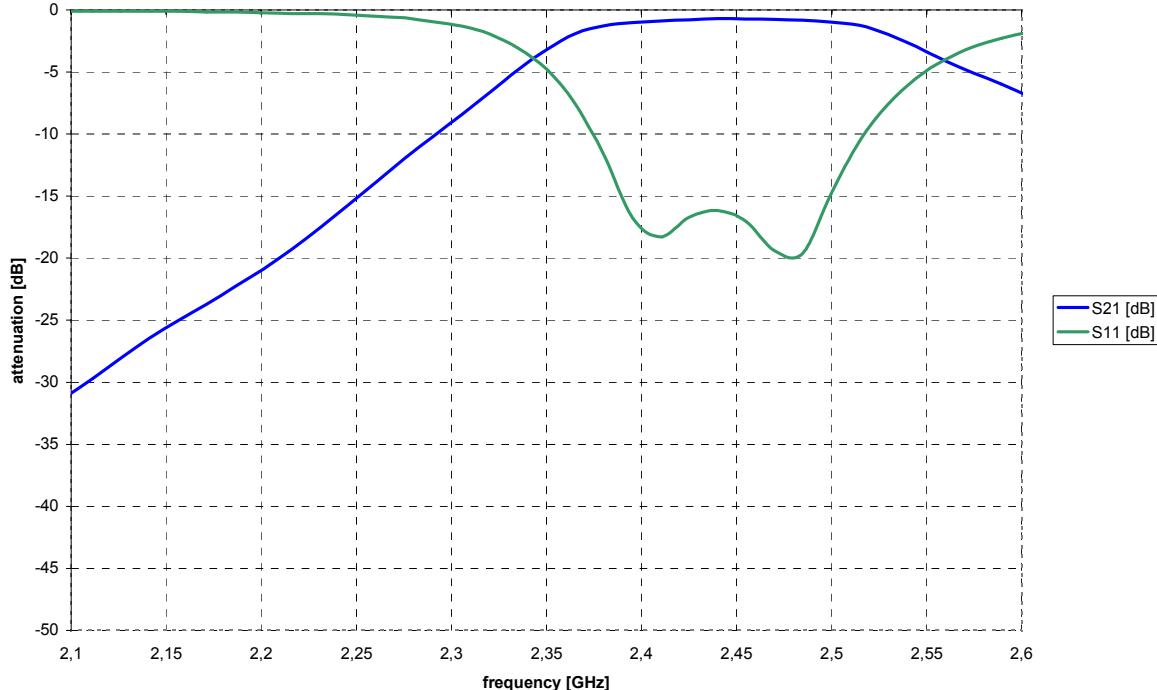


Preliminary Datasheet
Characteristics

		min.	typ.	max.	
Center frequency	f_c	-	2.450	-	GHz
Insertion loss	α_{IL}	1.0	1.0	1.5	dB
Passband (2400- 2500)	B	100			MHz
Amplitude ripple (peak - peak)	$\Delta\alpha$	0.4	0.8	0.8	dB
Standing wave ratio	SWR	1.5	1.5	2.0	
Impedance	Z	50	50		Ω
Attenuation					
at DC to 880 MHz		50	55		dB
at 880 to 960 MHz		45	50		dB
at 960 to 1990 MHz		34	40		dB
at 1990 to 2100 MHz		20	25		dB
at 2100 to 2170 MHz		13	18		dB
at 3200 to 4000 MHz		18	25		dB
at 4000 to 4200 MHz		25	30		dB
at 4200 to 4960 MHz		20	25		dB
at 4960 to 5787 MHz		13	20		dB

Maximum ratings

IEC climatic category (IEC 68-1)	- 40 / + 90/56	
Operating temperature	T_{op} - 40 / + 85	°C

Typical passband characteristic


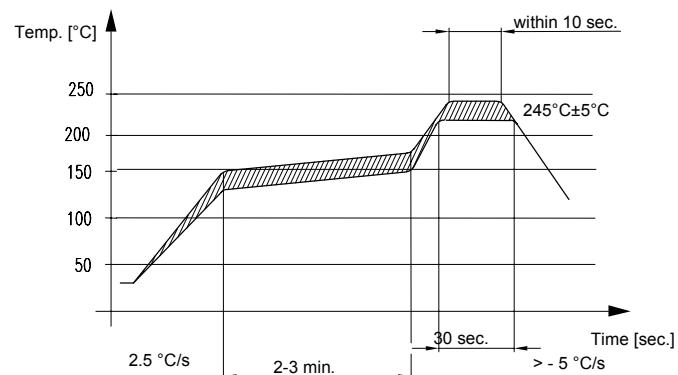
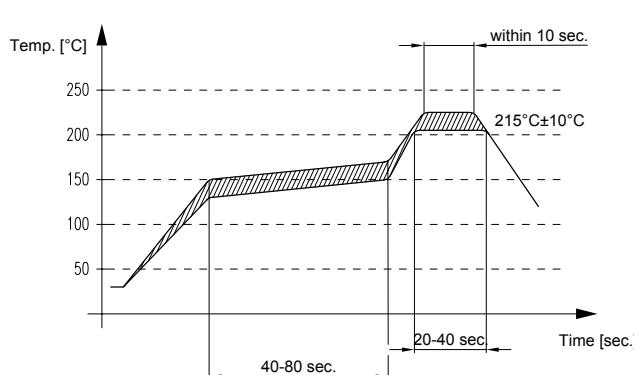
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Preliminary Datasheet
Processing information

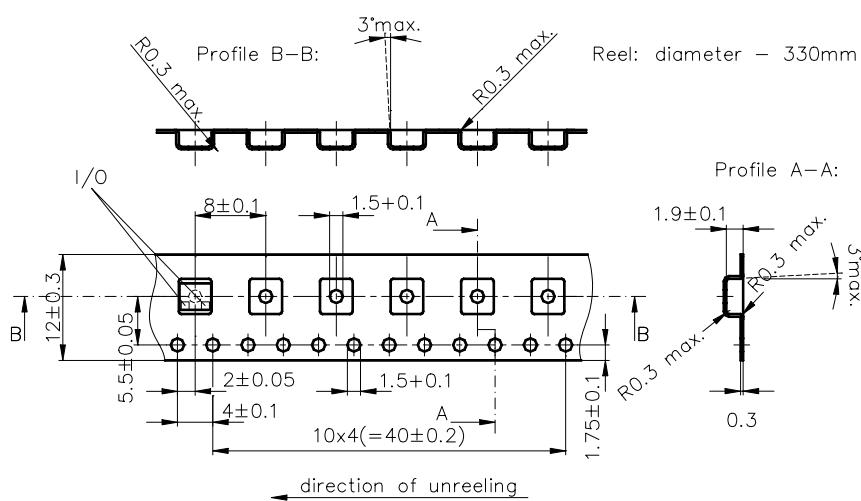
- Wettability to IEC 68-2-58: $\geq 75\%$ (after aging)

Soldering Requirements

	Profile for eutectic SnPb solder paste	Profile for leadfree solder paste	
Soldering type	reflow	reflow	
Maximum soldering temperature (measuring point on top surface of the component)	235 (max. 2 sec.) 225 (max. 10 sec.)	260 (max. 2 sec.) 250 (max. 10 sec.)	°C °C

Recommended soldering conditions (infrared):

Delivery mode

- Blister tape acc. to IEC 286-3, grey
- Pieces/tape: 4000



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